Chip back potential is the level which bulk silicon is maintained by on-chip connection, or it is the level to which the chip back must be connected when specifically stated below. If no potential is given the chip back should be isolated.

**.078”**



**.078”**

**Top Material: Al**

**Backside Material: Ti/Ni/Ag**

**Bond Pad Size: G = .004 X .006”**

 **C = .004 X .008”**

**Backside Potential: ANODE**

**Mask Ref:**

**APPROVED BY: DK DIE SIZE .078” X .078” DATE: 1/26/22**

**MFG: NEW ENGLAND SEMI THICKNESS .012” P/N: 2N2323**

**DG 10.1.2**

#### Rev B, 7/1